PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
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EPAS ID: PAT6865104

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
ZVI OR-BACH	08/14/2021
BRIAN CRONQUIST	08/15/2021
DEEPAK SEKAR	08/14/2021

RECEIVING PARTY DATA

Name:	MONOLITHIC 3D INC.
Street Address:	1662 COVE POINT RD
City:	KLAMATH FALLS
State/Country:	OREGON
Postal Code:	97601

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	17402527

CORRESPONDENCE DATA

Fax Number:

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 4088399533
Email: Brian@MonolithIC3D.com
Correspondent Name: BRIAN CRONQUIST
Address Line 1: 1662 COVE POINT RD
Address Line 4: KLAMATH FALLS, OREGON 97601

ATTORNEY DOCKET NUMBER:	MONOLITHIC3D-C-ISCON2
NAME OF SUBMITTER:	BRIAN CRONQUIST
SIGNATURE:	/Brian Cronquist/
DATE SIGNED:	08/15/2021

Total Attachments: 3
source=MonolithIC3D_C-IScon2_Assignment_Zvi--signed#page1.tif
source=MonolithIC3D_C-IScon2_Assignment_Deepak signed#page1.tif
source=MonolithIC3D_C-IScon2_Assignment_Brian signed#page1.tif

ASSIGNMENT

Whereas, I, **Zvi Or-Bach (hereinafter referred to as Assignor(s)), residing in Haifa, Israel;** have made a certain invention, and executed United States Patent Application entitled:

A MULTILEVEL SEMICONDUCTOR DEVICE AND STRUCTURE WITH IMAGE SENSORS

as described in US Application Serial No. 17/tbd and filed on or about August 15, 2021; and

Whereas, MonolithIC 3D™ Inc., a company located at 1662 Cove Point Road, Klamath Falls, OR 97601 (hereinafter called "Assignee"), desires to acquire the entire right, title, and interest in the application and the invention, and to any applications, patents and/or utility model registrations filed or obtained therefor in every Country (hereinafter called the "Designated Countries").

Now therefore, for valuable consideration, receipt of which is hereby acknowledged,

I/we, the above named Assignor(s), hereby sell, assign and transfer to the above named Assignee the entire right, title and interest to file and/or obtain any applications, patents and/or utility model registrations in the Designated Countries as regards the United States application and the invention disclosed therein (including rights of priority based on the United States application), and I/we will execute without further consideration all papers deemed necessary by the Assignee in connection with such applications, patents and/or utility model registrations in the Designated Countries when called upon to do so by the Assignee.

Signed and Sealed:

INVENTOR:

צבי אור-בך

DATE on 08 / 14 / 2021

(Zvi | | **Or-Bach)**
First Name | Middle Initial | Last Name

ASSIGNMENT

Whereas, I, **Deepak Sekar (hereinafter referred to as Assignor(s)), residing in Sunnyvale, California;** have made a certain invention, and executed United States Patent Application entitled:

A MULTILEVEL SEMICONDUCTOR DEVICE AND STRUCTURE WITH IMAGE SENSORS

as described in U.S. Application Serial No. 17/tbd filed on or about August 15, 2021; and

Whereas, MonolithIC 3D™ Inc., a company located at 1662 Cove Point Road, Klamath Falls, OR 97601 (hereinafter called "Assignee"), desires to acquire the entire right, title, and interest in the application and the invention, and to any applications, patents and/or utility model registrations filed or obtained therefor in every Country (hereinafter called the "Designated Countries").

Now therefore, for valuable consideration, receipt of which is hereby acknowledged,

I/we, the above named Assignor(s), hereby sell, assign and transfer to the above named Assignee the entire right, title and interest to file and/or obtain any applications, patents and/or utility model registrations in the Designated Countries as regards the United States application and the invention disclosed therein (including rights of priority based on the United States application), and I/we will execute without further consideration all papers deemed necessary by the Assignee in connection with such applications, patents and/or utility model registrations in the Designated Countries when called upon to do so by the Assignee.

Signed and Sealed:

INVENTOR:

DATE on 08 / 14 / 2021

(Deepak		**Sekar)**
First Name	Middle Initial	Last Name

ASSIGNMENT

Whereas, I, **Brian Cronquist (hereinafter referred to as Assignor(s)), residing in Klamath Falls, Oregon;** have made a certain invention, and executed United States Patent Application entitled:

A MULTILEVEL SEMICONDUCTOR DEVICE AND STRUCTURE WITH IMAGE SENSORS

as described in US Application Serial No. 17/tbd filed on or about August 15, 2021; and

Whereas, MonolithIC 3D™ Inc., a company located at 1662 Cove Point Road, Klamath Falls, OR 97601 (hereinafter called "Assignee"), desires to acquire the entire right, title, and interest in the application and the invention, and to any applications, patents and/or utility model registrations filed or obtained therefor in every Country (hereinafter called the "Designated Countries").

Now therefore, for valuable consideration, receipt of which is hereby acknowledged,

I/we, the above named Assignor(s), hereby sell, assign and transfer to the above named Assignee the entire right, title and interest to file and/or obtain any applications, patents and/or utility model registrations in the Designated Countries as regards the United States application and the invention disclosed therein (including rights of priority based on the United States application), and I/we will execute without further consideration all papers deemed necessary by the Assignee in connection with such applications, patents and/or utility model registrations in the Designated Countries when called upon to do so by the Assignee.

Signed and Sealed:

INVENTOR:

DATE on 15 August 2021

(Brian		**Cronquist)**
First Name	Middle Initial	Last Name